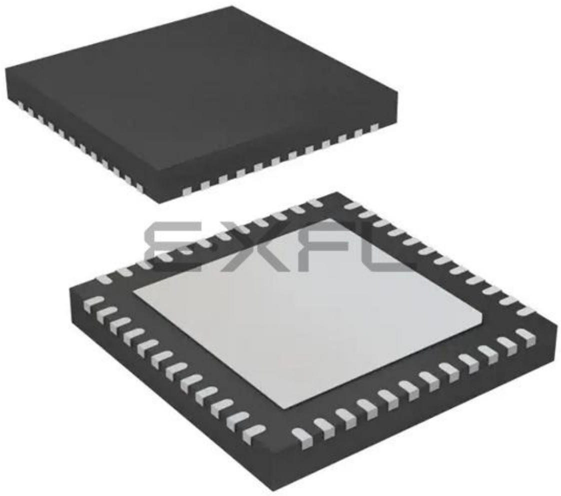

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-UFQFN Exposed Pad
Supplier Device Package	48-UQFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep256mc504-i-mv

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X AND PIC24EPXXXGP/MC20X PRODUCT FAMILIES

The device names, pin counts, memory sizes and peripheral availability of each device are listed in Table 1 (General Purpose Families) and Table 2 (Motor Control Families). Their pinout diagrams appear on the following pages.

TABLE 1: dsPIC33EPXXXGP50X and PIC24EPXXXGP20X GENERAL PURPOSE FAMILIES

Device	Page Erase Size (Instructions)	Program Flash Memory (Kbytes)	RAM (Kbyte)	Remappable Peripherals							I^2C^{TM}	CRC Generator	10-Bit/12-Bit ADC (Channels)	Op Amps/Comparators	CTMU	PTG	I/O Pins	Pins	Packages
				16-Bit/32-Bit Timers	Input Capture	Output Compare	UART	SPI(2)	ECAN™ Technology	External Interrupts(3)									
PIC24EP32GP202	512	32	4	5	4	4	2	2	—	3	2	1	6	2/3(1)	Yes	Yes	21	28	SPDIP, SOIC, SSOP(4), QFN-S
PIC24EP64GP202	1024	64	8																
PIC24EP128GP202	1024	128	16																
PIC24EP256GP202	1024	256	32																
PIC24EP512GP202	1024	512	48																
PIC24EP32GP203	512	32	4	5	4	4	2	2	—	3	2	1	8	3/4	Yes	Yes	25	36	VTLA
PIC24EP64GP203	1024	64	8																
PIC24EP32GP204	512	32	4	5	4	4	2	2	—	3	2	1	9	3/4	Yes	Yes	35	44/48	VTLA(4), TQFP, QFN, UQFN
PIC24EP64GP204	1024	64	8																
PIC24EP128GP204	1024	128	16																
PIC24EP256GP204	1024	256	32																
PIC24EP512GP204	1024	512	48																
PIC24EP64GP206	1024	64	8	5	4	4	2	2	—	3	2	1	16	3/4	Yes	Yes	53	64	TQFP, QFN
PIC24EP128GP206	1024	128	16																
PIC24EP256GP206	1024	256	32																
PIC24EP512GP206	1024	512	48																
dsPIC33EP32GP502	512	32	4	5	4	4	2	2	1	3	2	1	6	2/3(1)	Yes	Yes	21	28	SPDIP, SOIC, SSOP(4), QFN-S
dsPIC33EP64GP502	1024	64	8																
dsPIC33EP128GP502	1024	128	16																
dsPIC33EP256GP502	1024	256	32																
dsPIC33EP512GP502	1024	512	48																
dsPIC33EP32GP503	512	32	4	5	4	4	2	2	1	3	2	1	8	3/4	Yes	Yes	25	36	VTLA
dsPIC33EP64GP503	1024	64	8																
dsPIC33EP32GP504	512	32	4	5	4	4	2	2	1	3	2	1	9	3/4	Yes	Yes	35	44/48	VTLA(4), TQFP, QFN, UQFN
dsPIC33EP64GP504	1024	64	8																
dsPIC33EP128GP504	1024	128	16																
dsPIC33EP256GP504	1024	256	32																
dsPIC33EP512GP504	1024	512	48																
dsPIC33EP64GP506	1024	64	8	5	4	4	2	2	1	3	2	1	16	3/4	Yes	Yes	53	64	TQFP, QFN
dsPIC33EP128GP506	1024	128	16																
dsPIC33EP256GP506	1024	256	32																
dsPIC33EP512GP506	1024	512	48																

Note 1: On 28-pin devices, Comparator 4 does not have external connections. Refer to **Section 25.0 "Op Amp/Comparator Module"** for details.
2: Only SPI2 is remappable.
3: INT0 is not remappable.
4: The SSOP and VTLA packages are not available for devices with 512 Kbytes of memory.

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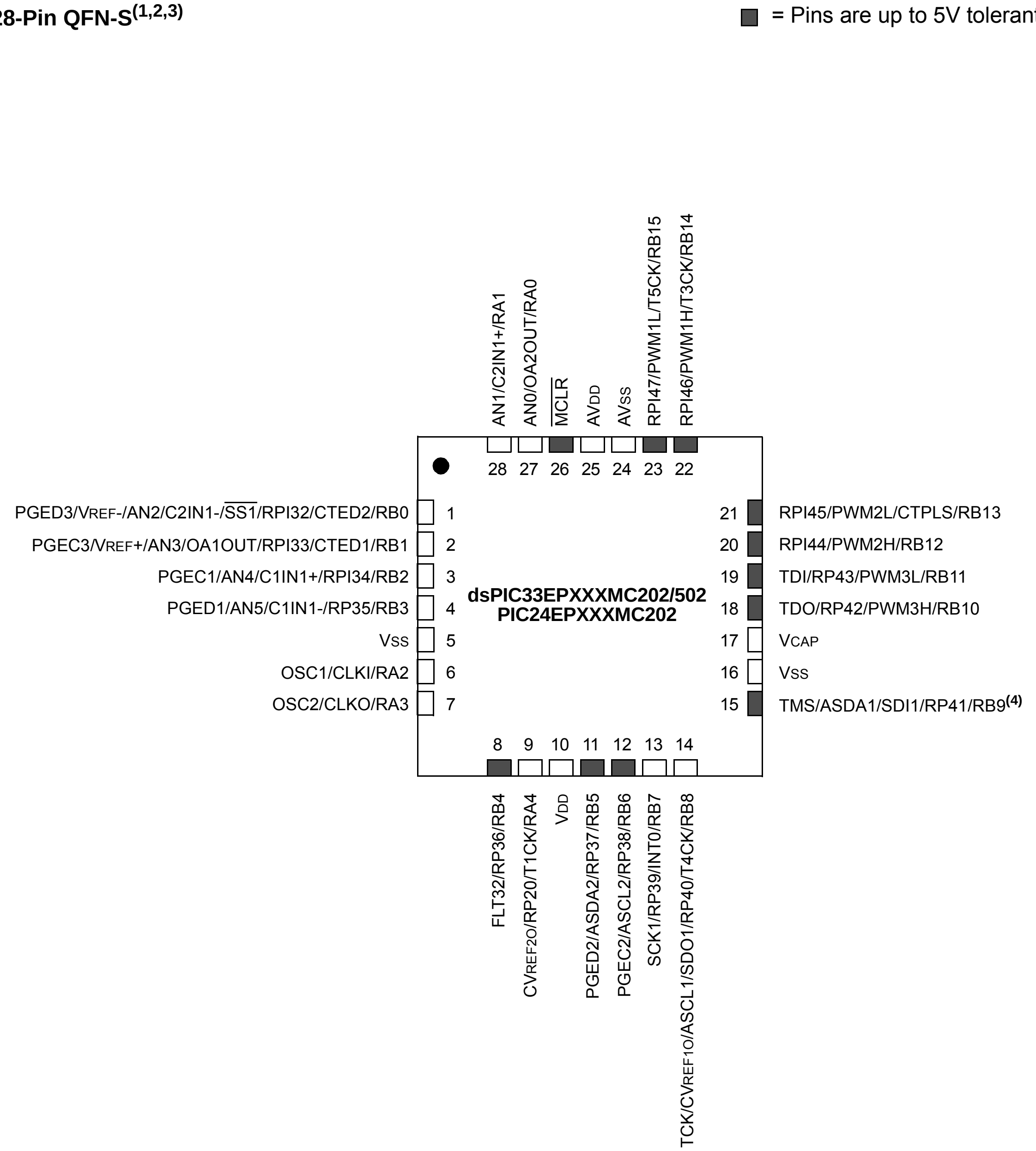
Pin Diagrams (Continued)

28-Pin QFN-S(1,2,3)



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

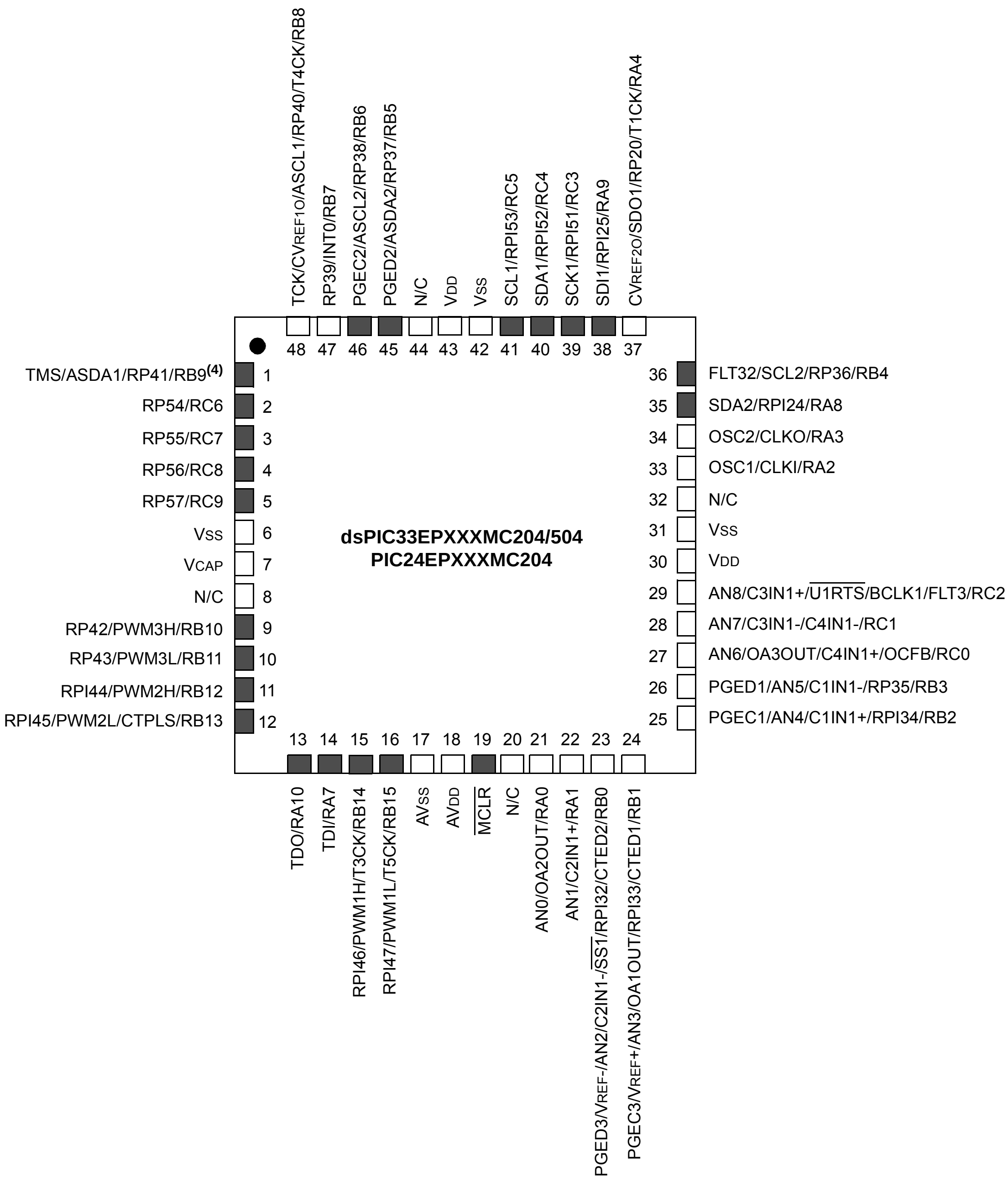
3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

Pin Diagrams (Continued)

48-Pin UQFN(1,2,3)

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

4.1.1 PROGRAM MEMORY ORGANIZATION

The program memory space is organized in word-addressable blocks. Although it is treated as 24 bits wide, it is more appropriate to think of each address of the program memory as a lower and upper word, with the upper byte of the upper word being unimplemented. The lower word always has an even address, while the upper word has an odd address (Figure 4-6).

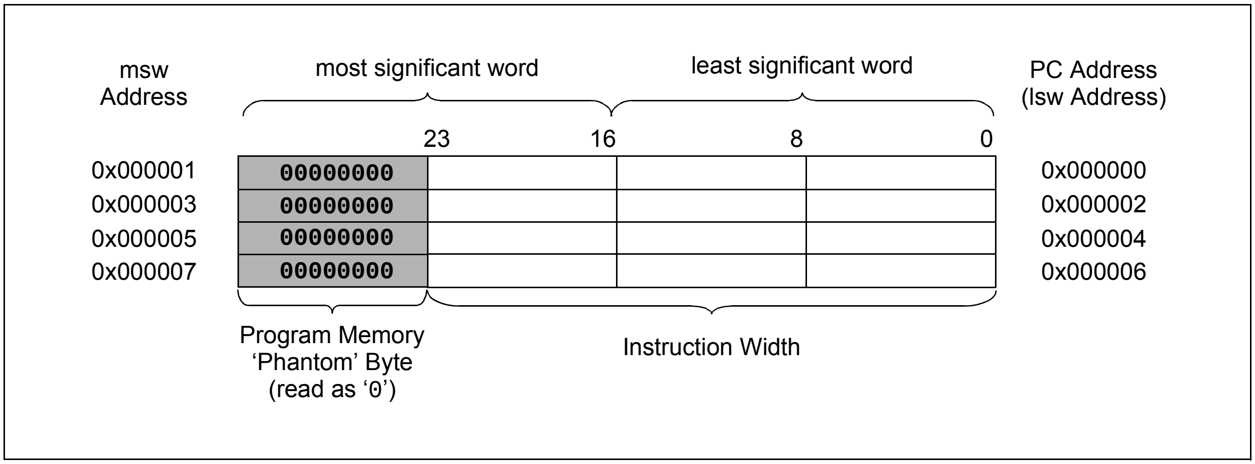
Program memory addresses are always word-aligned on the lower word and addresses are incremented, or decremented by two, during code execution. This arrangement provides compatibility with data memory space addressing and makes data in the program memory space accessible.

4.1.2 INTERRUPT AND TRAP VECTORS

All dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices reserve the addresses between 0x000000 and 0x000200 for hard-coded program execution vectors. A hardware Reset vector is provided to redirect code execution from the default value of the PC on device Reset to the actual start of code. A `GOTO` instruction is programmed by the user application at address, 0x000000, of Flash memory, with the actual address for the start of code at address, 0x000002, of Flash memory.

A more detailed discussion of the Interrupt Vector Tables (IVTs) is provided in **Section 7.1 "Interrupt Vector Table"**.

FIGURE 4-6: PROGRAM MEMORY ORGANIZATION



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4.4.4 SOFTWARE STACK

The W15 register serves as a dedicated Software Stack Pointer (SSP) and is automatically modified by exception processing, subroutine calls and returns; however, W15 can be referenced by any instruction in the same manner as all other W registers. This simplifies reading, writing and manipulating of the Stack Pointer (for example, creating stack frames).

> **Note:** To protect against misaligned stack accesses, W15<0> is fixed to '0' by the hardware.

W15 is initialized to 0x1000 during all Resets. This address ensures that the SSP points to valid RAM in all dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices, and permits stack availability for non-maskable trap exceptions. These can occur before the SSP is initialized by the user software. You can reprogram the SSP during initialization to any location within Data Space.

The Software Stack Pointer always points to the first available free word and fills the software stack working from lower toward higher addresses. Figure 4-19 illustrates how it pre-decrements for a stack pop (read) and post-increments for a stack push (writes).

When the PC is pushed onto the stack, PC<15:0> are pushed onto the first available stack word, then PC<22:16> are pushed into the second available stack location. For a PC push during any `CALL` instruction, the MSB of the PC is zero-extended before the push, as shown in Figure 4-19. During exception processing, the MSB of the PC is concatenated with the lower 8 bits of the CPU STATUS Register, SR. This allows the contents of SRL to be preserved automatically during interrupt processing.

> **Note 1:** To maintain system Stack Pointer (W15) coherency, W15 is never subject to (EDS) paging, and is therefore restricted to an address range of 0x0000 to 0xFFFF. The same applies to the W14 when used as a Stack Frame Pointer (SFA = 1).
>
> **2:** As the stack can be placed in, and can access X and Y spaces, care must be taken regarding its use, particularly with regard to local automatic variables in a C development environment

FIGURE 4-19: CALL STACK FRAME

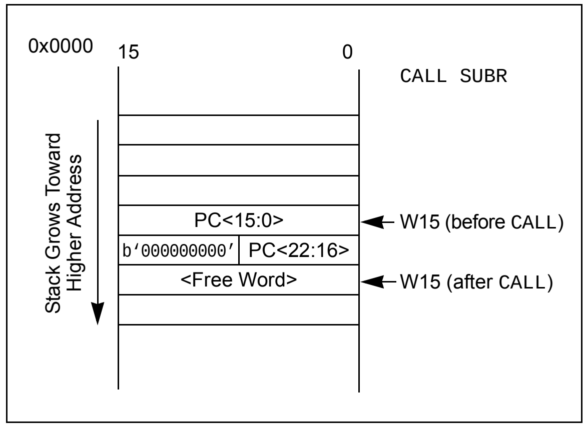
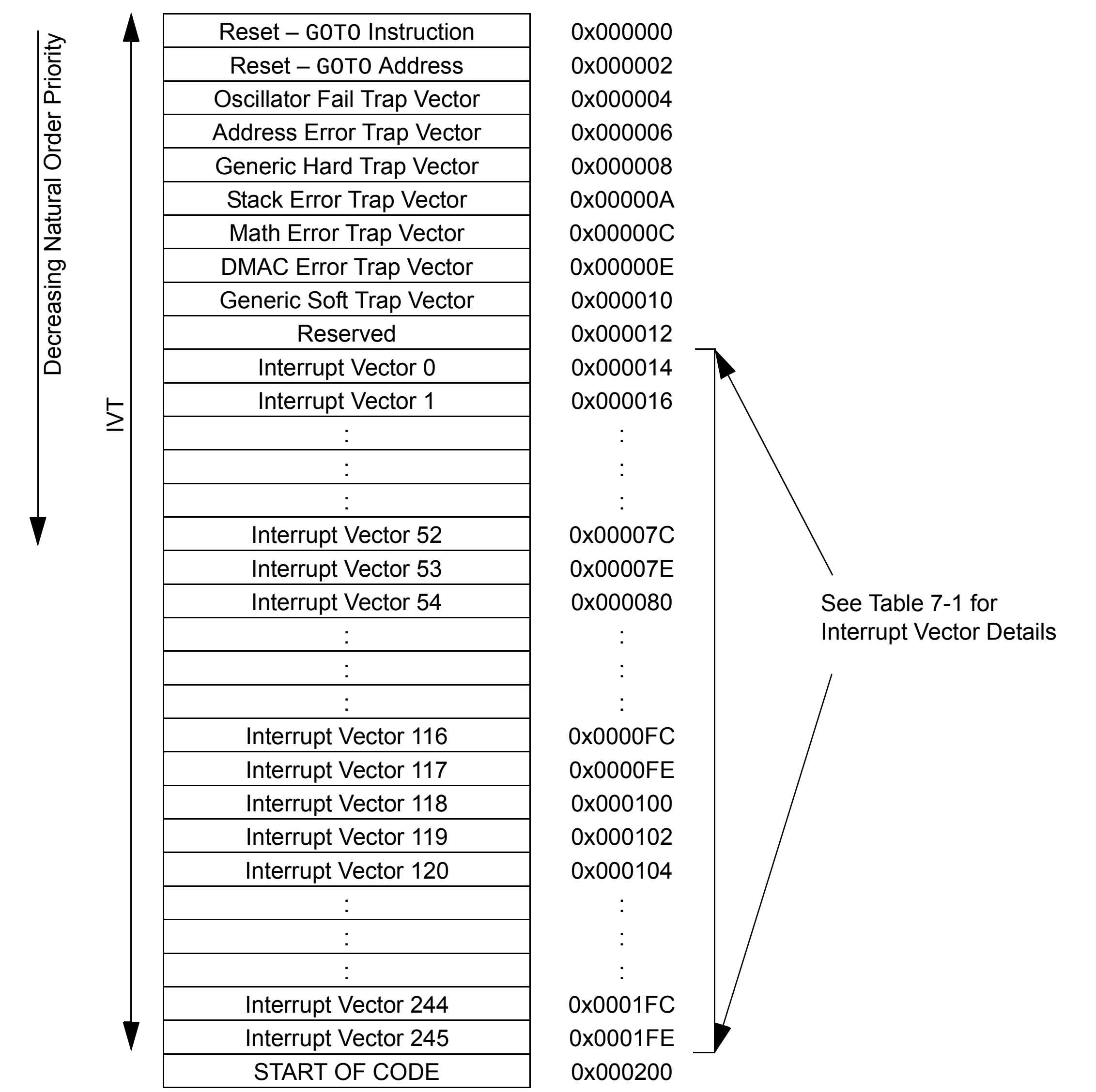


FIGURE 7-1: dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X AND PIC24EPXXXGP/MC20X INTERRUPT VECTOR TABLE



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11.1.1 OPEN-DRAIN CONFIGURATION

In addition to the PORTx, LATx and TRISx registers for data control, port pins can also be individually configured for either digital or open-drain output. This is controlled by the Open-Drain Control register, ODCx, associated with each port. Setting any of the bits configures the corresponding pin to act as an open-drain output.

The open-drain feature allows the generation of outputs other than V_{DD} by using external pull-up resistors. The maximum open-drain voltage allowed on any pin is the same as the maximum V_{IH} specification for that particular pin.

See the **"Pin Diagrams"** section for the available 5V tolerant pins and Table 30-11 for the maximum V_{IH} specification for each pin.

11.2 Configuring Analog and Digital Port Pins

The ANSELx register controls the operation of the analog port pins. The port pins that are to function as analog inputs or outputs must have their corresponding ANSELx and TRISx bits set. In order to use port pins for I/O functionality with digital modules, such as Timers, UARTs, etc., the corresponding ANSELx bit must be cleared.

The ANSELx register has a default value of 0xFFFF; therefore, all pins that share analog functions are analog (not digital) by default.

Pins with analog functions affected by the ANSELx registers are listed with a buffer type of analog in the Pinout I/O Descriptions (see Table 1-1).

If the TRISx bit is cleared (output) while the ANSELx bit is set, the digital output level (V_{OH} or V_{OL}) is converted by an analog peripheral, such as the ADC module or comparator module.

When the PORTx register is read, all pins configured as analog input channels are read as cleared (a low level).

Pins configured as digital inputs do not convert an analog input. Analog levels on any pin defined as a digital input (including the ANx pins) can cause the input buffer to consume current that exceeds the device specifications.

11.2.1 I/O PORT WRITE/READ TIMING

One instruction cycle is required between a port direction change or port write operation and a read operation of the same port. Typically this instruction would be a `NOP`, as shown in Example 11-1.

11.3 Input Change Notification (ICN)

The Input Change Notification function of the I/O ports allows devices to generate interrupt requests to the processor in response to a Change-of-State (COS) on selected input pins. This feature can detect input Change-of-States even in Sleep mode, when the clocks are disabled. Every I/O port pin can be selected (enabled) for generating an interrupt request on a Change-of-State.

Three control registers are associated with the Change Notification (CN) functionality of each I/O port. The CNENx registers contain the CN interrupt enable control bits for each of the input pins. Setting any of these bits enables a CN interrupt for the corresponding pins.

Each I/O pin also has a weak pull-up and a weak pull-down connected to it. The pull-ups and pull-downs act as a current source or sink source connected to the pin and eliminate the need for external resistors when push button, or keypad devices are connected. The pull-ups and pull-downs are enabled separately, using the CNPUx and the CNPDx registers, which contain the control bits for each of the pins. Setting any of the control bits enables the weak pull-ups and/or pull-downs for the corresponding pins.

Note:	Pull-ups and pull-downs on Change Notification pins should always be disabled when the port pin is configured as a digital output.

EXAMPLE 11-1: PORT WRITE/READ EXAMPLE

```
MOV   0xFF00, W0   ; Configure PORTB<15:8>
                   ; as inputs
MOV   W0, TRISB    ; and PORTB<7:0>
                   ; as outputs
NOP                ; Delay 1 cycle
BTSS  PORTB, #13   ; Next Instruction
```


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REGISTER 16-7: PWMCONx: PWMx CONTROL REGISTER

HS/HC-0	HS/HC-0	HS/HC-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
FLTSTAT(1)	CLSTAT(1)	TRGSTAT	FLTIEN	CLIEN	TRGIEN	ITB(2)	MDCS(2)
bit 15							bit 8

R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
DTC1	DTC0	DTCP(3)	—	MTBS	CAM(2,4)	XPRES(5)	IUE(2)
bit 7							bit 0

Legend:	HC = Hardware Clearable bit	HS = Hardware Settable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **FLTSTAT:** Fault Interrupt Status bit(1)
1 = Fault interrupt is pending
0 = No Fault interrupt is pending
This bit is cleared by setting FLTIEN = 0.

bit 14 **CLSTAT:** Current-Limit Interrupt Status bit(1)
1 = Current-limit interrupt is pending
0 = No current-limit interrupt is pending
This bit is cleared by setting CLIEN = 0.

bit 13 **TRGSTAT:** Trigger Interrupt Status bit
1 = Trigger interrupt is pending
0 = No trigger interrupt is pending
This bit is cleared by setting TRGIEN = 0.

bit 12 **FLTIEN:** Fault Interrupt Enable bit
1 = Fault interrupt is enabled
0 = Fault interrupt is disabled and the FLTSTAT bit is cleared

bit 11 **CLIEN:** Current-Limit Interrupt Enable bit
1 = Current-limit interrupt is enabled
0 = Current-limit interrupt is disabled and the CLSTAT bit is cleared

bit 10 **TRGIEN:** Trigger Interrupt Enable bit
1 = A trigger event generates an interrupt request
0 = Trigger event interrupts are disabled and the TRGSTAT bit is cleared

bit 9 **ITB:** Independent Time Base Mode bit(2)
1 = PHASEx register provides time base period for this PWM generator
0 = PTPER register provides timing for this PWM generator

bit 8 **MDCS:** Master Duty Cycle Register Select bit(2)
1 = MDC register provides duty cycle information for this PWM generator
0 = PDCx register provides duty cycle information for this PWM generator

Note 1: Software must clear the interrupt status here and in the corresponding IFSx bit in the interrupt controller.
2: These bits should not be changed after the PWMx is enabled (PTEN = 1).
3: DTC<1:0> = 11 for DTCP to be effective; otherwise, DTCP is ignored.
4: The Independent Time Base (ITB = 1) mode must be enabled to use Center-Aligned mode. If ITB = 0, the CAM bit is ignored.
5: To operate in External Period Reset mode, the ITB bit must be ‘1’ and the CLMOD bit in the FCLCONx register must be ‘0’.

REGISTER 17-10: INDX1HLD: INDEX COUNTER 1 HOLD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INDXHLD<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INDXHLD<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **INDXHLD<15:0>:** Hold Register for Reading and Writing INDX1CNTH bits

REGISTER 17-11: QEI1ICH: QEI1 INITIALIZATION/CAPTURE HIGH WORD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QEIIC<31:24>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QEIIC<23:16>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **QEIIC<31:16>:** High Word Used to Form 32-Bit Initialization/Capture Register (QEI1IC) bits

REGISTER 17-12: QEI1ICL: QEI1 INITIALIZATION/CAPTURE LOW WORD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QEIIC<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QEIIC<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **QEIIC<15:0>:** Low Word Used to Form 32-Bit Initialization/Capture Register (QEI1IC) bits

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REGISTER 24-6: PTGSDLIM: PTG STEP DELAY LIMIT REGISTER(1,2)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGSDLIM<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGSDLIM<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **PTGSDLIM<15:0>:** PTG Step Delay Limit Register bits
Holds a PTG Step delay value representing the number of additional PTG clocks between the start of a Step command and the completion of a Step command.

Note 1: A base Step delay of one PTG clock is added to any value written to the PTGSDLIM register (Step Delay = (PTGSDLIM) + 1).

2: This register is read-only when the PTG module is executing Step commands (PTGEN = 1 and PTGSTRT = 1).

REGISTER 24-7: PTGC0LIM: PTG COUNTER 0 LIMIT REGISTER(1)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGC0LIM<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGC0LIM<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **PTGC0LIM<15:0>:** PTG Counter 0 Limit Register bits
May be used to specify the loop count for the `PTGJMPC0` Step command or as a limit register for the General Purpose Counter 0.

Note 1: This register is read-only when the PTG module is executing Step commands (PTGEN = 1 and PTGSTRT = 1).

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REGISTER 25-4: CMxMSKSRC: COMPARATOR x MASK SOURCE SELECT CONTROL REGISTER

U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	RW-0
—	—	—	—	SELSRCC3	SELSRCC2	SELSRCC1	SELSRCC0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SELSRCB3	SELSRCB2	SELSRCB1	SELSRCB0	SELSRCA3	SELSRCA2	SELSRCA1	SELSRCA0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-12 **Unimplemented:** Read as ‘0’

bit 11-8 **SELSRCC<3:0>:** Mask C Input Select bits

1111 = FLT4
1110 = FLT2
1101 = PTGO19
1100 = PTGO18
1011 = Reserved
1010 = Reserved
1001 = Reserved
1000 = Reserved
0111 = Reserved
0110 = Reserved
0101 = PWM3H
0100 = PWM3L
0011 = PWM2H
0010 = PWM2L
0001 = PWM1H
0000 = PWM1L

bit 7-4 **SELSRCB<3:0>:** Mask B Input Select bits

1111 = FLT4
1110 = FLT2
1101 = PTGO19
1100 = PTGO18
1011 = Reserved
1010 = Reserved
1001 = Reserved
1000 = Reserved
0111 = Reserved
0110 = Reserved
0101 = PWM3H
0100 = PWM3L
0011 = PWM2H
0010 = PWM2L
0001 = PWM1H
0000 = PWM1L

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TABLE 30-11: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
	IIL	**Input Leakage Current**(1,2)					
DI50		I/O Pins 5V Tolerant(3)	-1	—	+1	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI51		I/O Pins Not 5V Tolerant(3)	-1	—	+1	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, -40°C ≤ TA ≤ +85°C
DI51a		I/O Pins Not 5V Tolerant(3)	-1	—	+1	μA	Analog pins shared with external reference pins, -40°C ≤ TA ≤ +85°C
DI51b		I/O Pins Not 5V Tolerant(3)	-1	—	+1	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, -40°C ≤ TA ≤ +125°C
DI51c		I/O Pins Not 5V Tolerant(3)	-1	—	+1	μA	Analog pins shared with external reference pins, -40°C ≤ TA ≤ +125°C
DI55		$\overline{\text{MCLR}}$	-5	—	+5	μA	VSS ≤ VPIN ≤ VDD
DI56		OSC1	-5	—	+5	μA	VSS ≤ VPIN ≤ VDD, XT and HS modes

Note 1: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

2: Negative current is defined as current sourced by the pin.

3: See the **"Pin Diagrams"** section for the 5V tolerant I/O pins.

4: VIL source < (VSS – 0.3). Characterized but not tested.

5: Non-5V tolerant pins VIH source > (VDD + 0.3), 5V tolerant pins VIH source > 5.5V. Characterized but not tested.

6: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.

7: Non-zero injection currents can affect the ADC results by approximately 4-6 counts.

8: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

FIGURE 30-19: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING CHARACTERISTICS

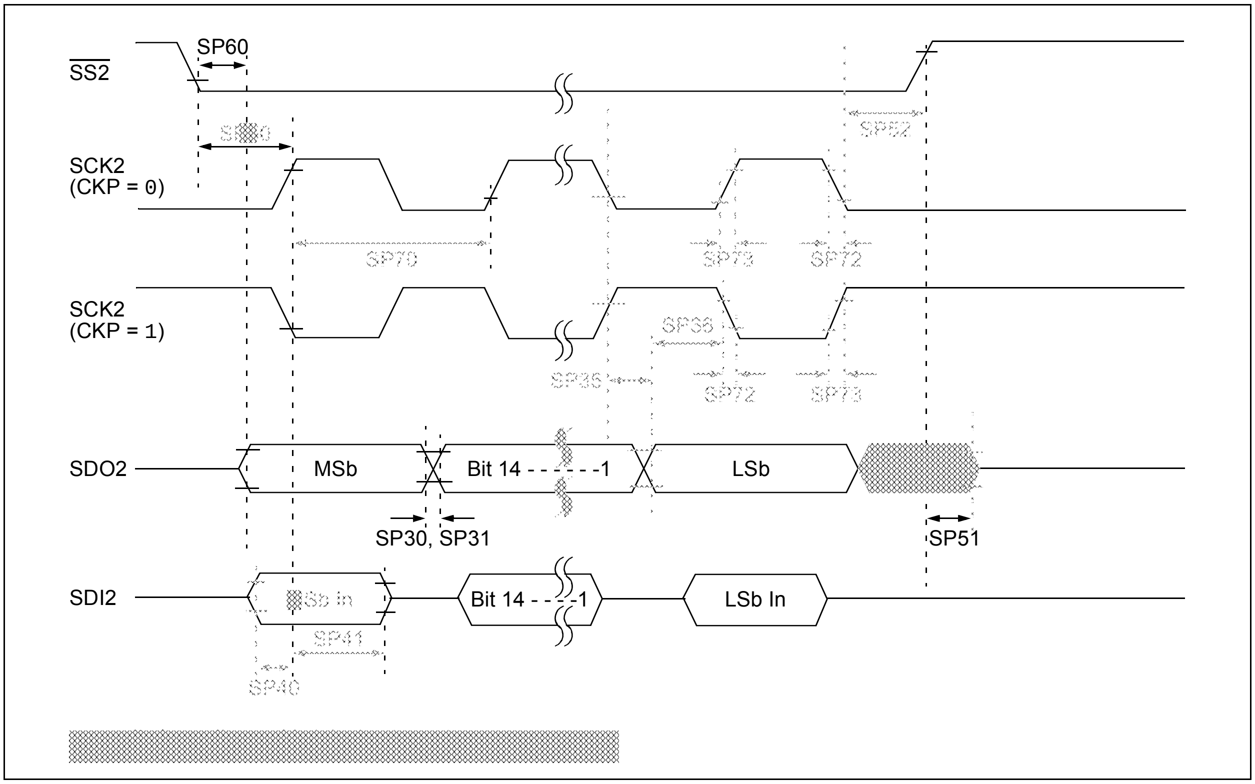

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FIGURE 30-20: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING CHARACTERISTICS

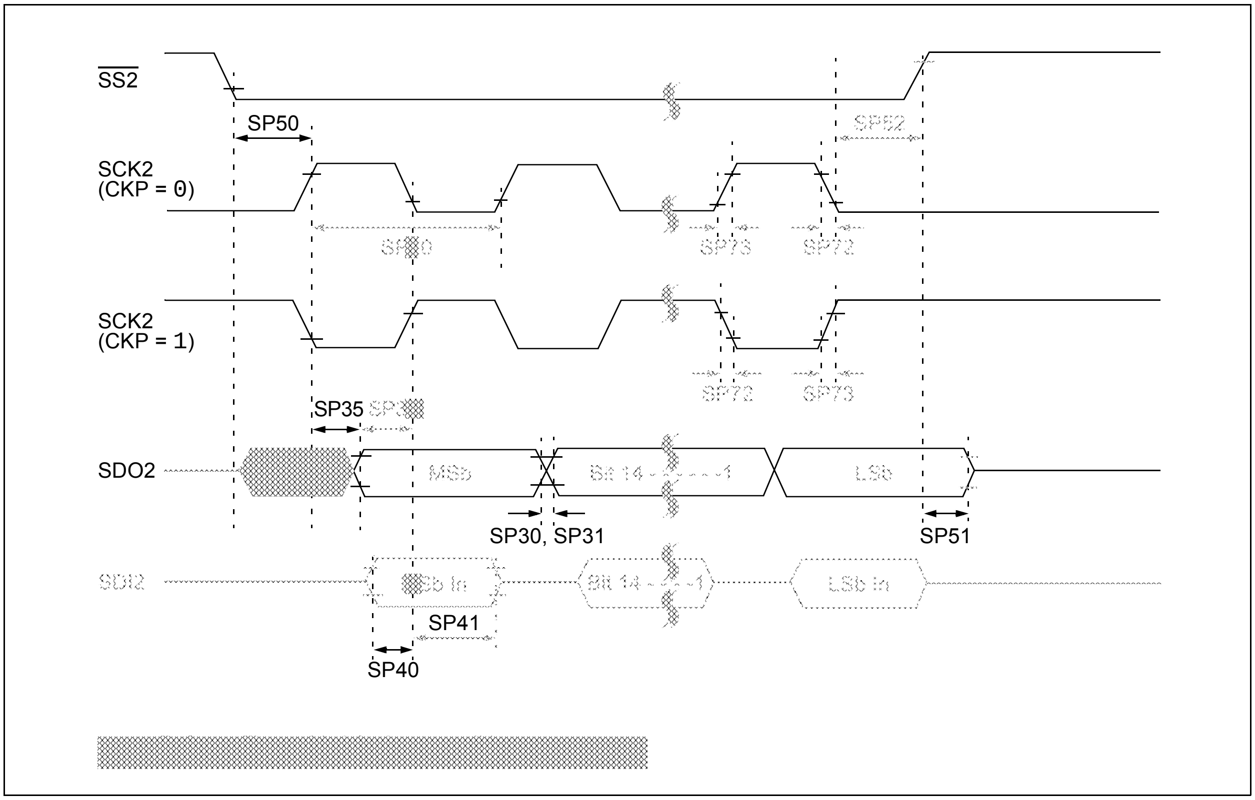

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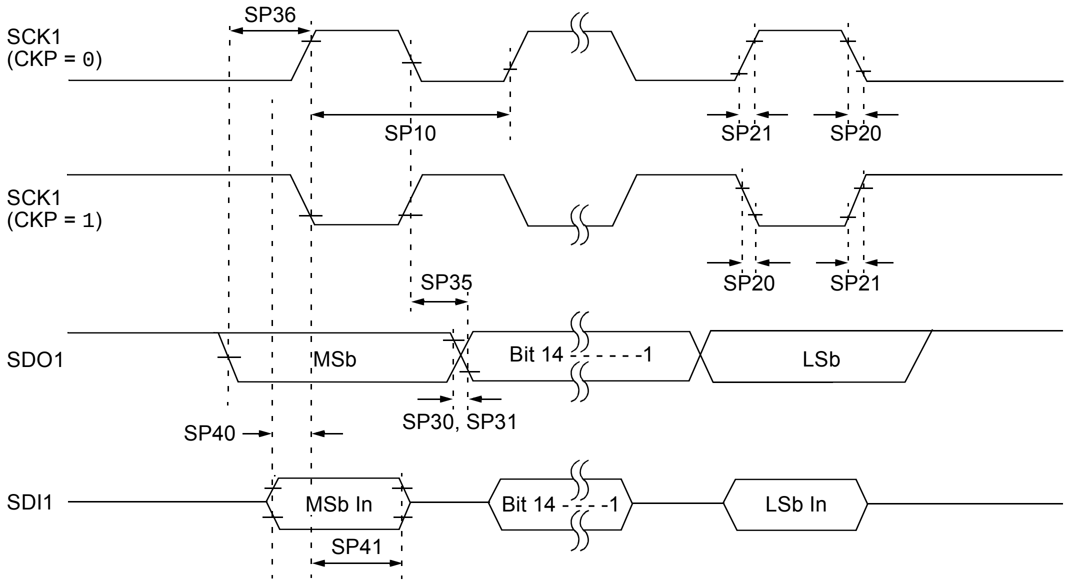
FIGURE 30-24: SPI1 MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-43: SPI1 MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	FscP	Maximum SCK1 Frequency	—	—	10	MHz	**(Note 3)**
SP20	TscF	SCK1 Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP21	TscR	SCK1 Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2sc, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.
2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.
3: The minimum clock period for SCK1 is 100 ns. The clock generated in Master mode must not violate this specification.
4: Assumes 50 pF load on all SPI1 pins.

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TABLE 30-60: ADC CONVERSION (12-BIT MODE) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)(1) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
Clock Parameters							
AD50	TAD	ADC Clock Period	117.6	—	—	ns	
AD51	tRC	ADC Internal RC Oscillator Period(2)	—	250	—	ns	
Conversion Rate							
AD55	tCONV	Conversion Time	—	14 TAD		ns	
AD56	FCNV	Throughput Rate	—	—	500	ksps	
AD57a	TSAMP	Sample Time when Sampling any ANx Input	3 TAD	—	—	—	
AD57b	TSAMP	Sample Time when Sampling the Op Amp Outputs (Configuration A and Configuration B)(4,5)	3 TAD	—	—	—	
Timing Parameters							
AD60	tPCS	Conversion Start from Sample Trigger(2,3)	2 TAD	—	3 TAD	—	Auto-convert trigger is not selected
AD61	tPSS	Sample Start from Setting Sample (SAMP) bit(2,3)	2 TAD	—	3 TAD	—	
AD62	tCSS	Conversion Completion to Sample Start (ASAM = 1)(2,3)	—	0.5 TAD	—	—	
AD63	tDPU	Time to Stabilize Analog Stage from ADC Off to ADC On(2,3)	—	—	20	µs	**(Note 6)**

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: Parameters are characterized but not tested in manufacturing.

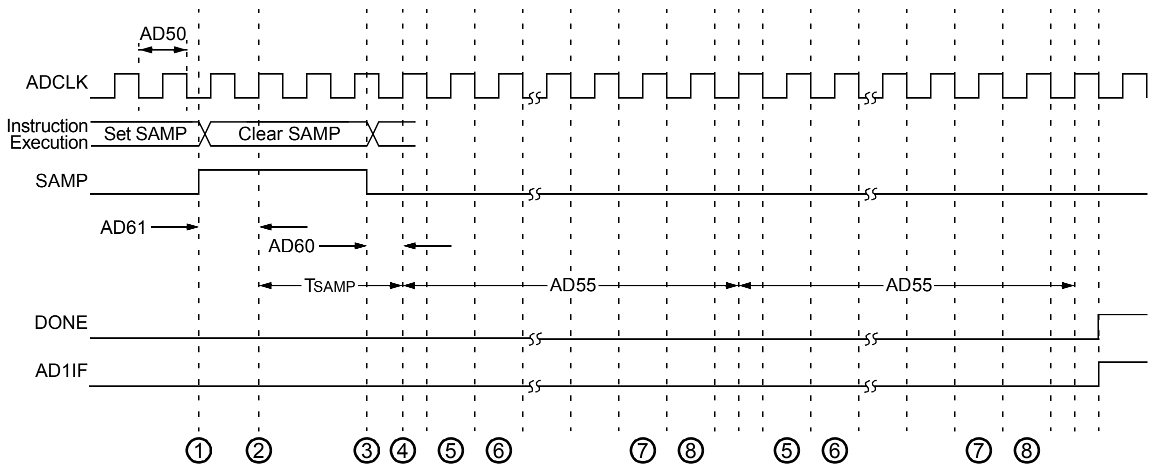
3: Because the sample caps will eventually lose charge, clock rates below 10 kHz may affect linearity performance, especially at elevated temperatures.

4: See Figure 25-6 for configuration information.

5: See Figure 25-7 for configuration information.

6: The parameter, tDPU, is the time required for the ADC module to stabilize at the appropriate level when the module is turned on (ADON (AD1CON1<15>) = 1). During this time, the ADC result is indeterminate.

FIGURE 30-37: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 0, SSRC<2:0> = 000, SSRCG = 0)



① – Software sets AD1CON1. SAMP to start sampling.

② – Sampling starts after discharge period. TSAMP is described in **"Analog-to-Digital Converter (ADC)"** (DS70621) in the *"dsPIC33/PIC24 Family Reference Manual"*.

③ – Software clears AD1CON1. SAMP to start conversion.

④ – Sampling ends, conversion sequence starts.

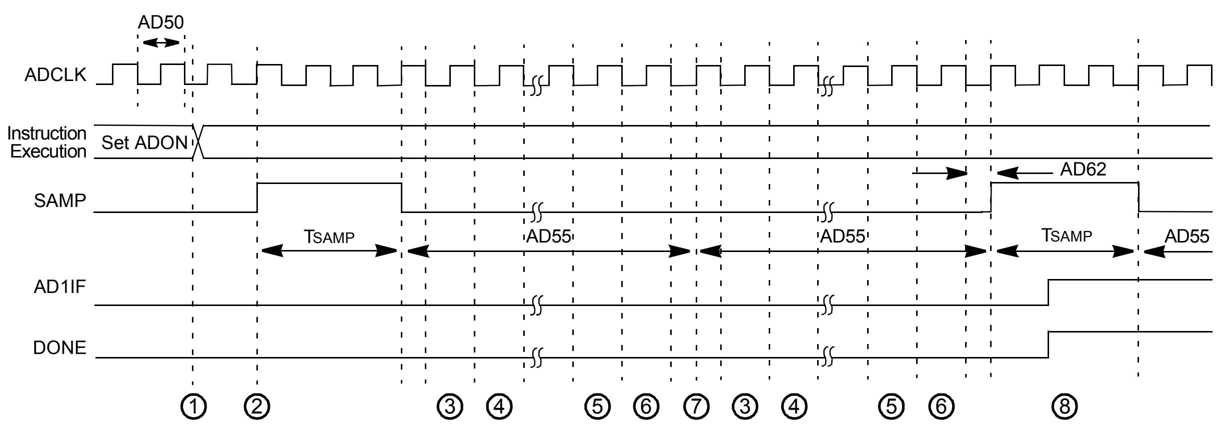
⑤ – Convert bit 9.

⑥ – Convert bit 8.

⑦ – Convert bit 0.

⑧ – One TAD for end of conversion.

FIGURE 30-38: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 1, SSRC<2:0> = 111, SSRCG = 0, SAMC<4:0> = 00010)



① – Software sets AD1CON1. ADON to start AD operation.

② – Sampling starts after discharge period. TSAMP is described in **"Analog-to-Digital Converter (ADC)"** (DS70621) in the *"dsPIC33/PIC24 Family Reference Manual"*.

③ – Convert bit 9.

④ – Convert bit 8.

⑤ – Convert bit 0.

⑥ – One TAD for end of conversion.

⑦ – Begin conversion of next channel.

⑧ – Sample for time specified by SAMC<4:0>.

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TABLE 31-12: ADC MODULE SPECIFICATIONS (12-BIT MODE)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
ADC Accuracy (12-Bit Mode)(1)							
HAD20a	Nr	Resolution(3)	12 Data Bits			bits	
HAD21a	INL	Integral Nonlinearity	-5.5	—	5.5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
HAD22a	DNL	Differential Nonlinearity	-1	—	1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
HAD23a	GERR	Gain Error	-10	—	10	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
HAD24a	EOFF	Offset Error	-5	—	5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
Dynamic Performance (12-Bit Mode)(2)							
HAD33a	FNYQ	Input Signal Bandwidth	—	—	200	kHz	

Note 1: These parameters are characterized, but are tested at 20 ksps only.
2: These parameters are characterized by similarity, but are not tested in manufacturing.
3: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

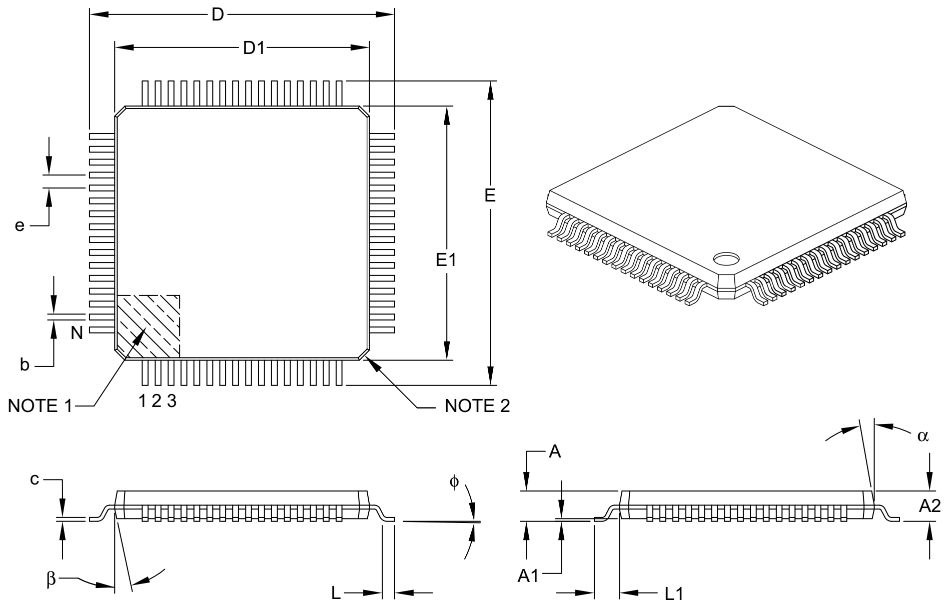
TABLE 31-13: ADC MODULE SPECIFICATIONS (10-BIT MODE)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
ADC Accuracy (10-Bit Mode)(1)							
HAD20b	Nr	Resolution(3)	10 Data Bits			bits	
HAD21b	INL	Integral Nonlinearity	-1.5	—	1.5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
HAD22b	DNL	Differential Nonlinearity	-0.25	—	0.25	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
HAD23b	GERR	Gain Error	-2.5	—	2.5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
HAD24b	EOFF	Offset Error	-1.25	—	1.25	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
Dynamic Performance (10-Bit Mode)(2)							
HAD33b	FNYQ	Input Signal Bandwidth	—	—	400	kHz	

Note 1: These parameters are characterized, but are tested at 20 ksps only.
2: These parameters are characterized by similarity, but are not tested in manufacturing.
3: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

64-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		64	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	φ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-085B

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